



Engineers' Society of Saint Paul

The Oldest Engineering Society in the State of Minnesota

P.O. Box 4764

Saint Paul, MN 55101

2018 SCHOLARSHIP APPLICATION

This application is used as a basis to award scholarships from the Engineer's Society of Saint Paul

Applications must be postmarked or received by Tuesday, January 8, 2019

Name _____

Current address _____

Phone _____ E-mail _____

Permanent address _____

ESSP Member Sponsor _____

ACADEMIC STATUS

Degree sought _____ Area(s) of interest/emphasis _____

Expected graduation date _____ Current GPA _____

Credits completed within Engineering Emphasis _____

RESUME

Please attach a one-page resume which lists your educational experience (undergraduate and graduate colleges/universities, dates attended, degrees received, etc.), work experience (employer name, job title, dates of employment, responsibilities, and hours per week).

FINANCIAL NEED (describe circumstances; list scholarships received (sponsors, dates, amounts))

PERSONAL STATEMENT

ESSP considers its scholarships to be investments in the future of Minnesota. Keeping your personal statement within a two-page limit, please explain why ESSP should make such an investment in you. You may wish to include answers to these questions: What are your activities and interests outside of the classroom? How did you become interested in engineering? What part of engineering interests you most? What type of job do you think you want following graduation?

Submit application package to:

Engineers' Society of St. Paul
P.O. Box 4764
Saint Paul, MN 55101

Or email to:

Michael Kraemer
mrkraemer50@gmail.com

or

Barritt Lovelace
blovelace@collinsengr.com

Application package must include:

- 1. Application form (please print double-sided)**
- 2. Unofficial transcript**
- 3. One-page resume**
- 4. Personal Statement (two-page limit)**
- 5. Proof of enrollment (attach a copy of your tuition receipt or current registration card)**

Applications must be postmarked or received by Tuesday, January 9, 2019.

NOTE: The names of students, fields of study, and related information are considered to be in the public domain and may be disclosed by ESSP in press releases, reports on the scholarship program, and similar documents. In addition, the student agrees that the information in this application may be released to organizations outside the Engineers' Society of St. Paul that award scholarships to engineering students.

I hereby state I meet the qualifications for consideration of the ESSP scholarship. I am a United States citizen. I have been and will be pursuing an engineering or an engineering-related degree through at least the spring 2018 semester. I will be registered for at least 12 credits for the spring 2018 semester. I am sponsored by an active member of ESSP.

I have read, and I understand the conditions of this application.

Signature

Date